

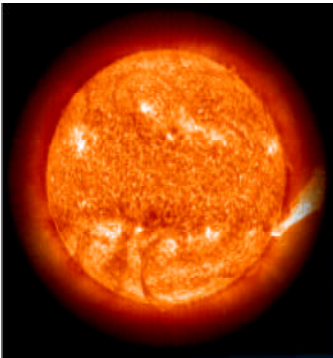
Development of imaging arrays for solar UV observations based on wide band-gap materials

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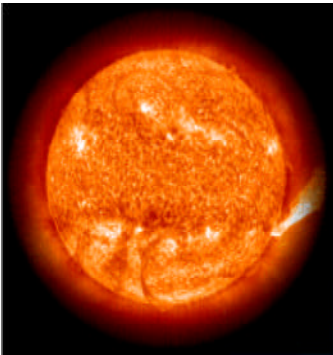




Outline of the talk

1. Introduction: Why new detectors?
2. Requirements for new detectors
3. Prospects towards new semiconductor devices
4. Prototype wide band-gap sensors: GaN, AlGaN devices
5. Efficiency measurements with new one-pixel devices





Conclusions of last years talk:

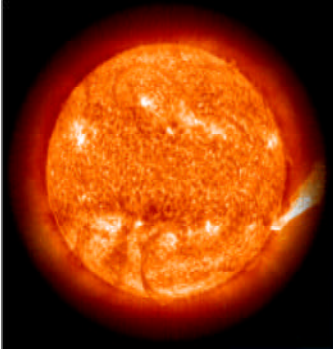
- SOHO UV instruments have been very stable due to the successful cleanliness program.

but

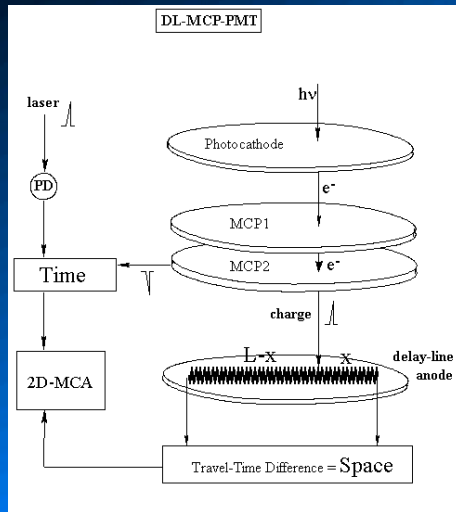
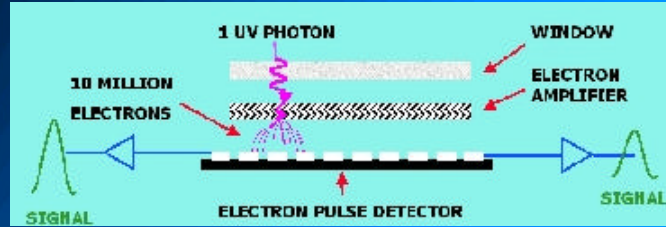
- SOHO UV detectors have been remarkably unstable.

Those were either channel plate devices, or (intensified) CCDs!

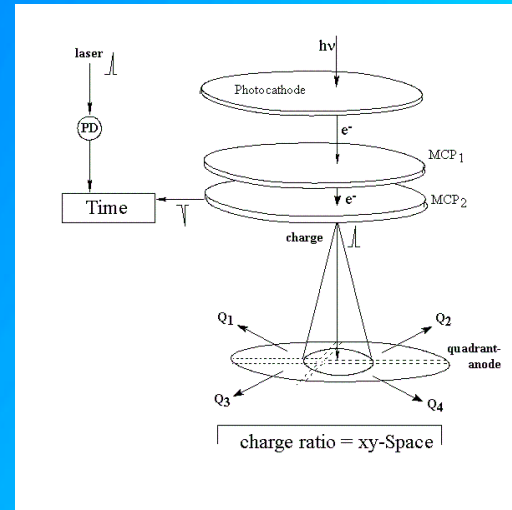




MCP detectors



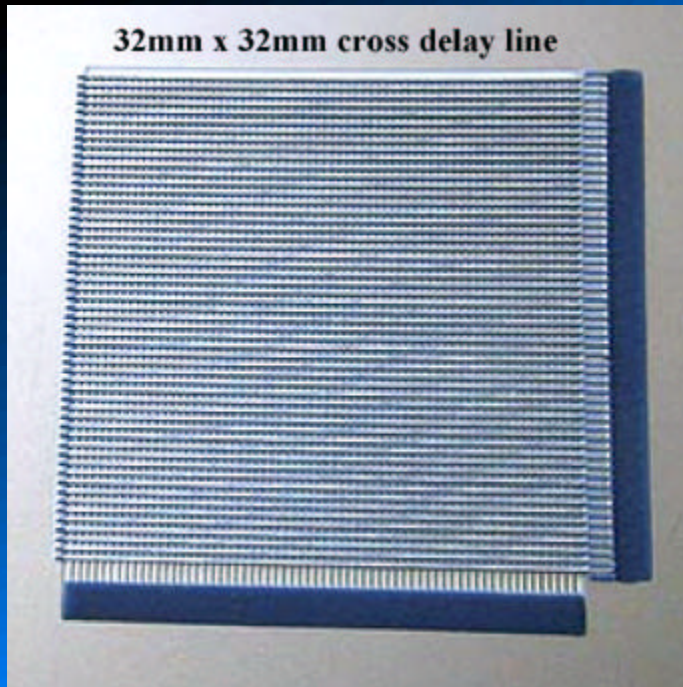
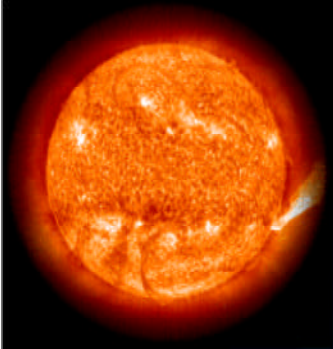
Cross delay line anode + time to digital converter



Cross strip anode + charge ratio centroiding



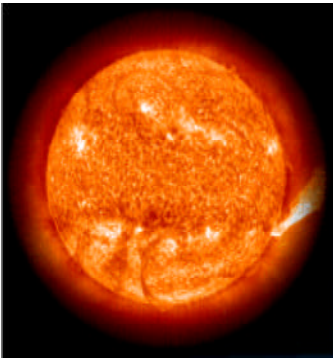
Anode design options



courtesy: O. Siegmund

- Wedge and strip anode
- Cross Delay line anode
- Cross strip anode
- CCD

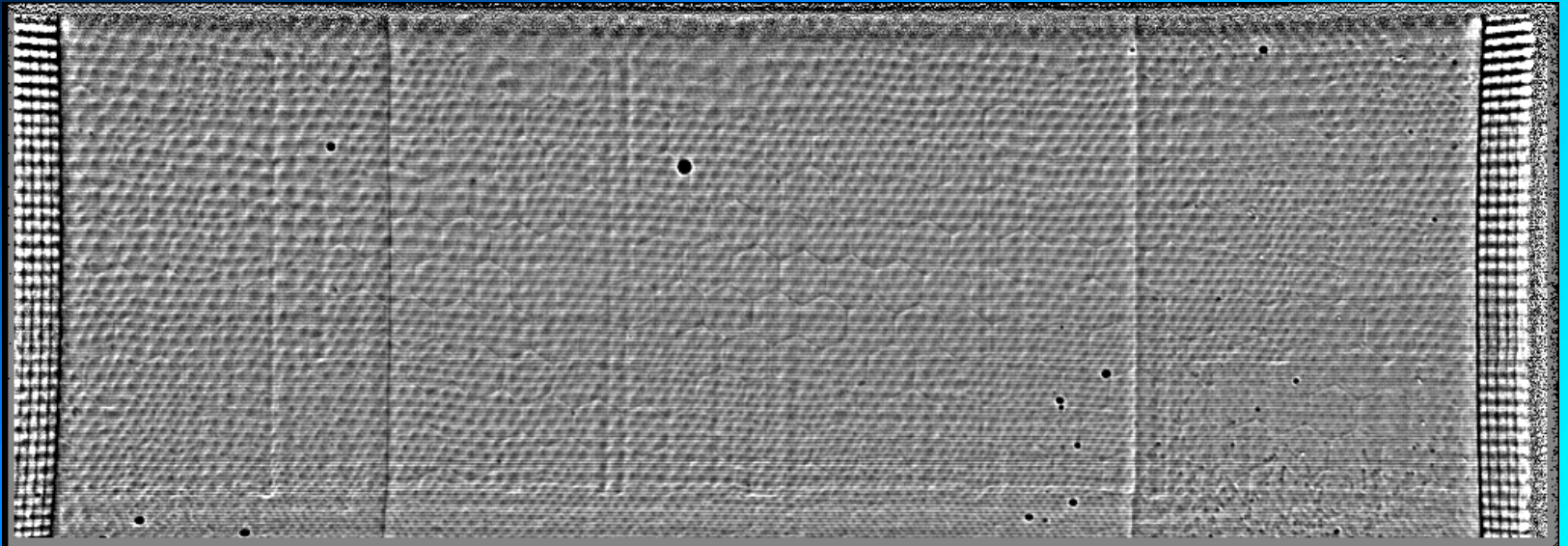


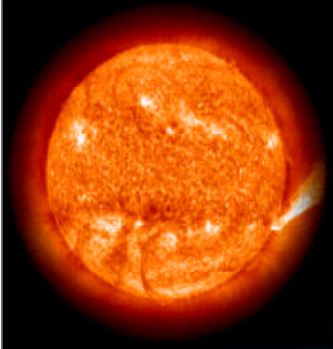


Example: flatfield of SUMER XDL detector

- Distortion
- ADC nonlinearity
- Multifiber bundles (hexagonal)
- Moire pattern (from 3 MCPs)
- Dead pores

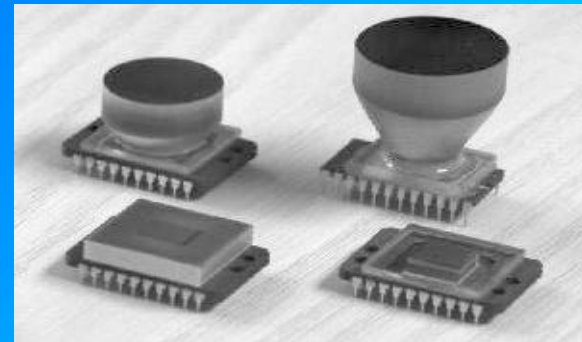
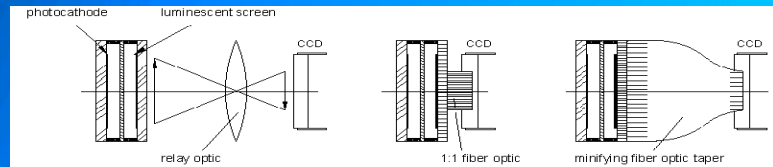
Unstable due to scrubbing!





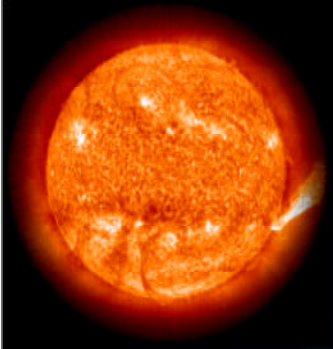
Intensified CCDs

MCP coupled to CCD via lens or fiber-optic taper



„Ultra Compact Design“

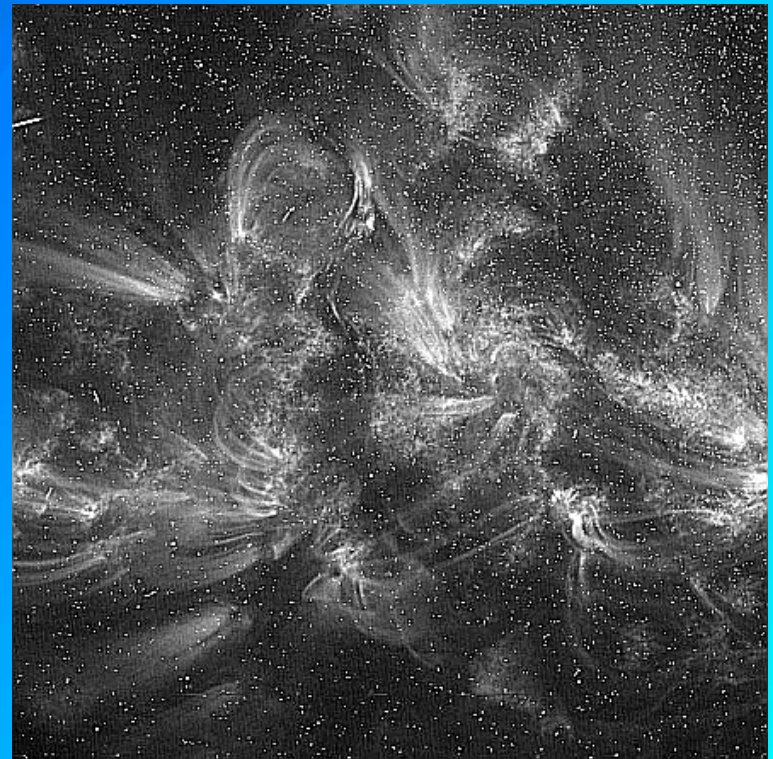
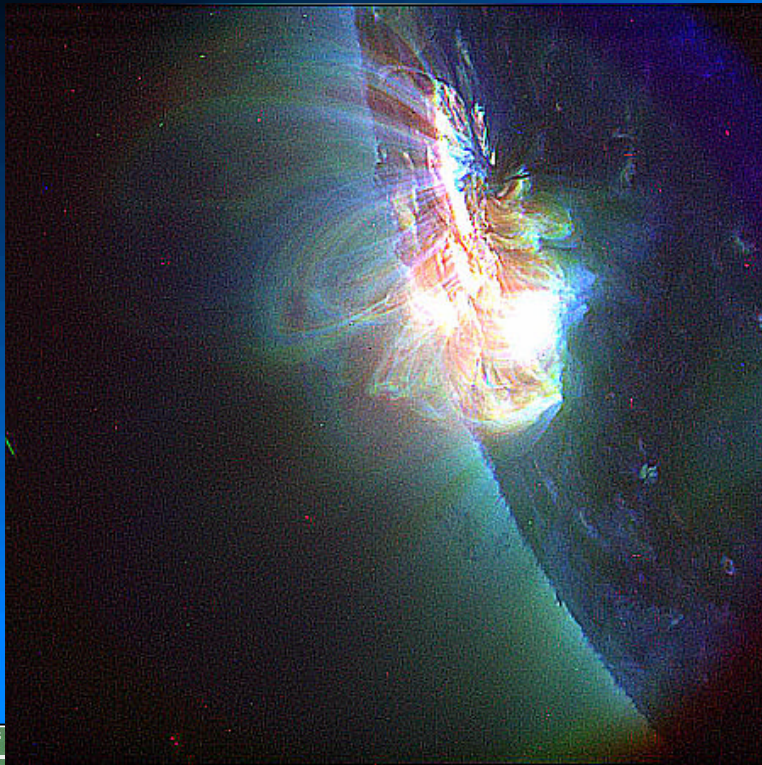


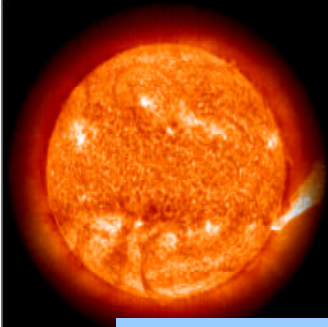


Quest for high resolution



0.5 arcsec
~ 350 km at Sun



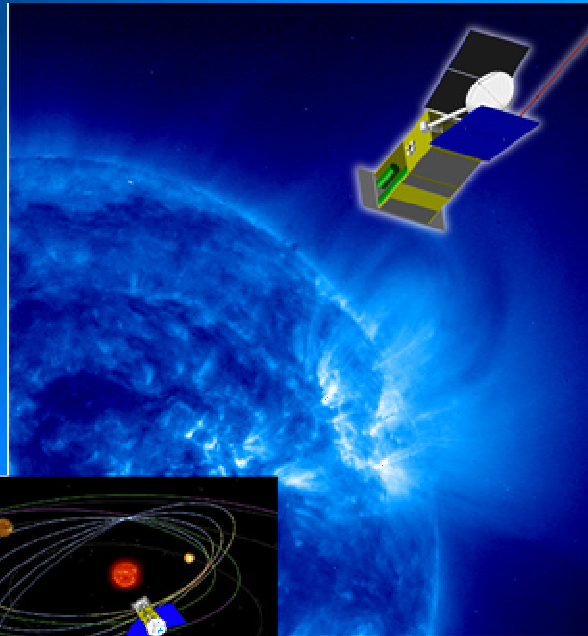


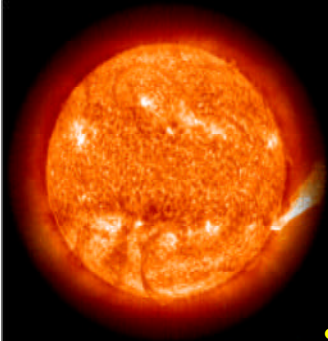
Solar Orbiter mission

High-resolution mission to the Sun and Inner Heliosphere

Payload instrumentation:

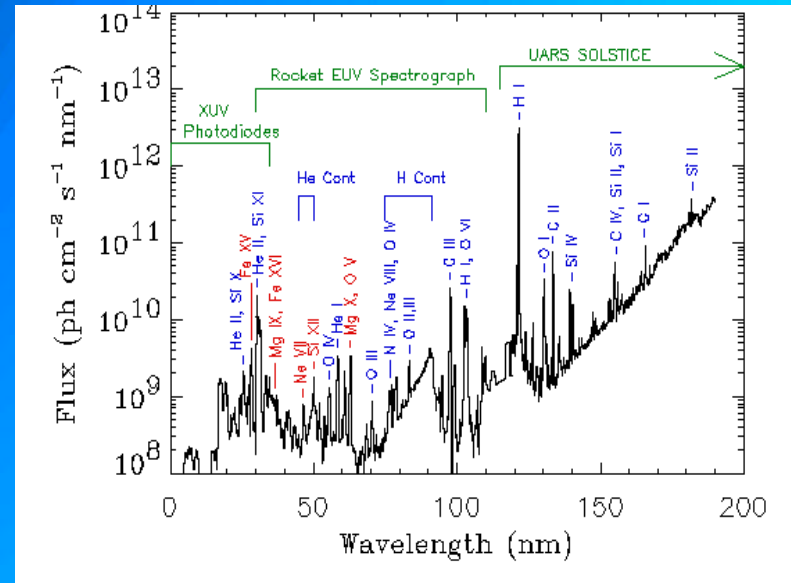
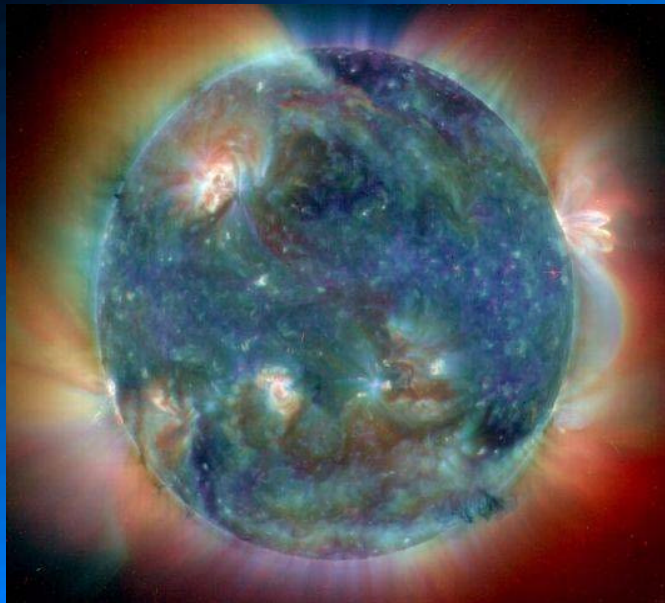
- o EUV spectrograph
- o EUV imagers
- o UV coronagraph





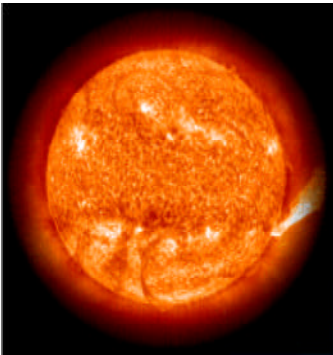
What are our goals?

- large pixel array
- radiation hard
- smallest pixel size
- high count rate
- sensitive in a huge wavelength range
- solar blind
- stable calibration
- low dark noise

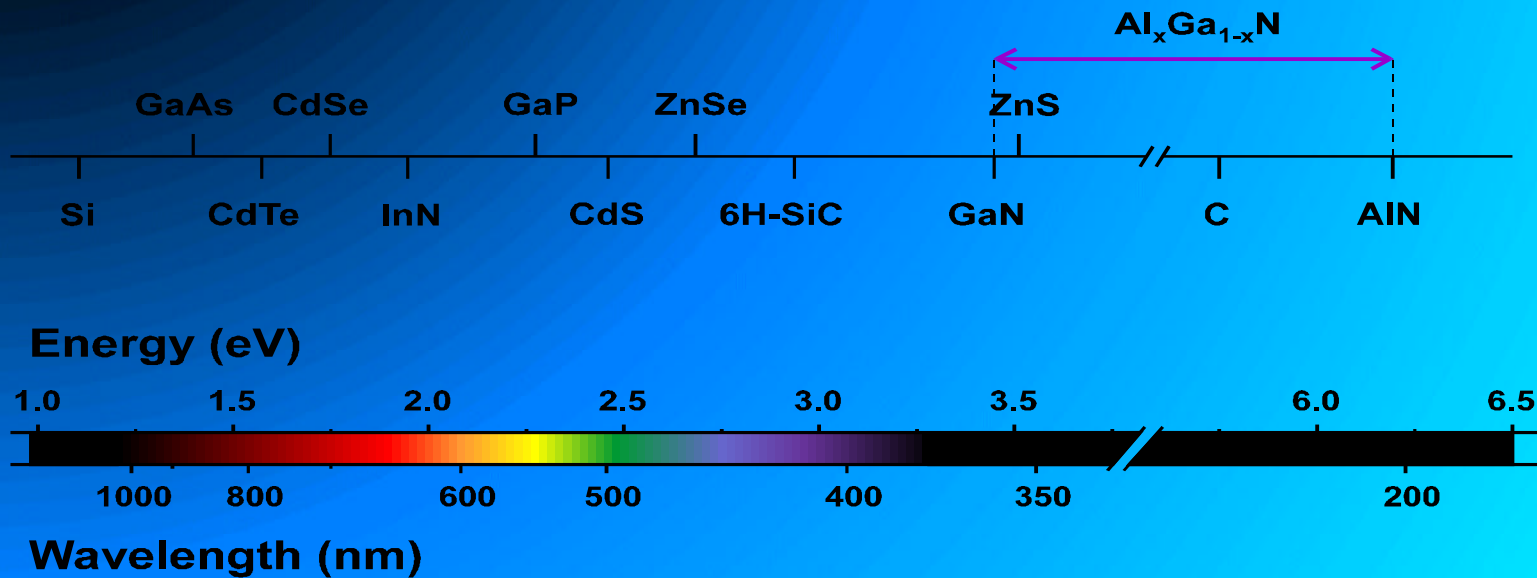


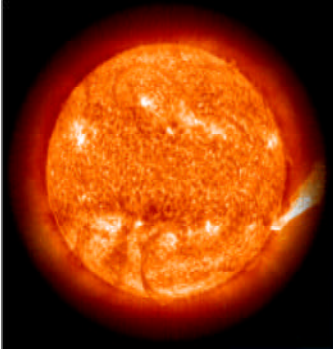
Imaging sensors with high sensitivity and resolution,
Large pixel format but smallest pixel size!





Wide band-gap materials



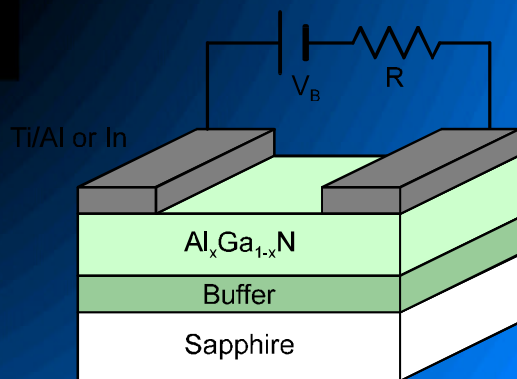
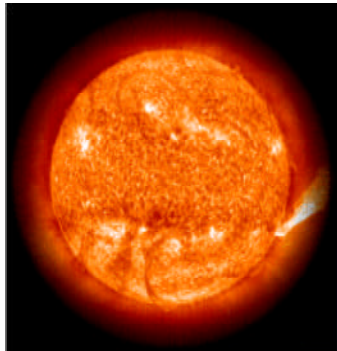


Advantages/disadvantages

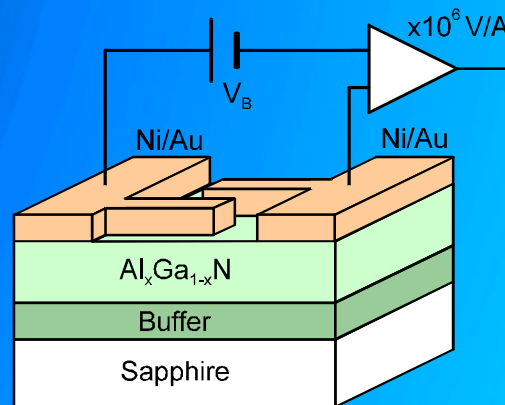
<u>Silicon Detectors</u>	<u>Wide Bandgap Detectors</u>
Need cooling to -60 C or less (Dark current & radiations)	Room temperature operations (simpler & cost-effective)
Contaminants stick and polymerize (cold trap)	Low contamination risk, long-term stability
Degradation of the charge transfer efficiency by ionizing radiation	Rad-hardness Whole mission lifetime increased
Cosmic ray hits plague the signal (points & strikes)	Smaller cross-section => less artifacts
QE insufficient, inhomogeneous, and unstable	Higher QE. Stability and flat-field improved
MCP Intensifiers needed	VUV sensitive
Minimal pixel size ~10 microns	Potentially much smaller
Most sensitive in visible, filters needed (fragile, absorbing UV)	Visible-Blind Some filters can be removed Gain in effective area



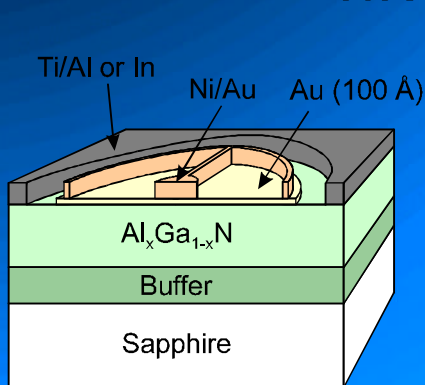
$\text{Al}_x\text{Ga}_{1-x}\text{N}$ Photodetector types



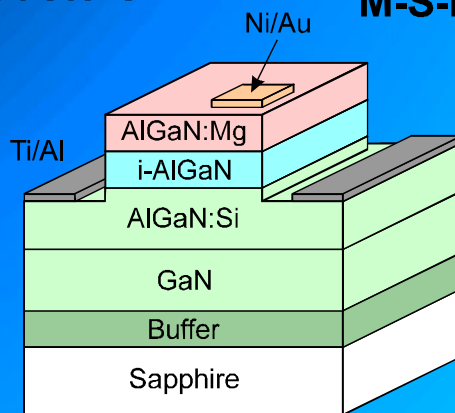
Photoconductors



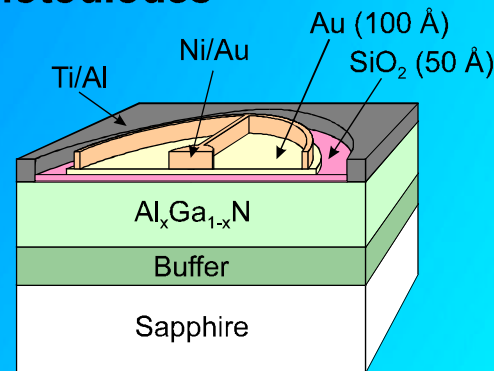
M-S-M Photodiodes



Schottky Photodiodes

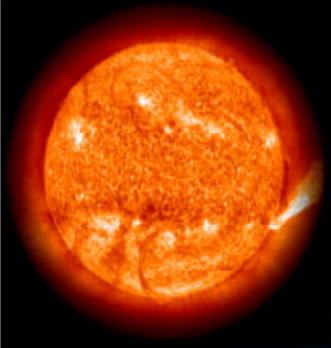


***p-i-n* Photodiodes**

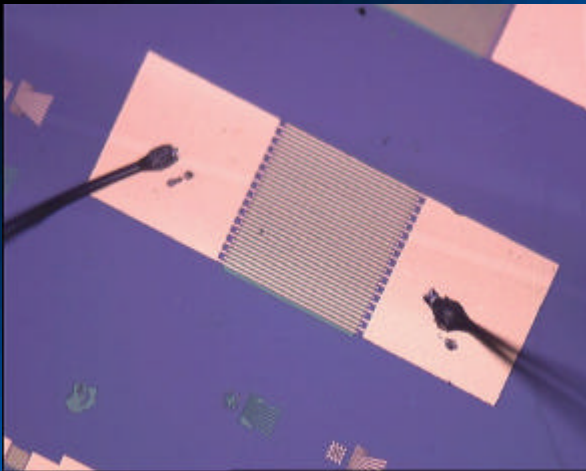


M-I-S Photodiodes

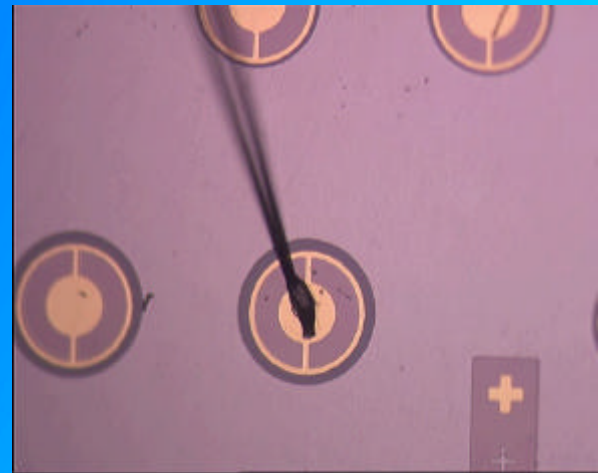




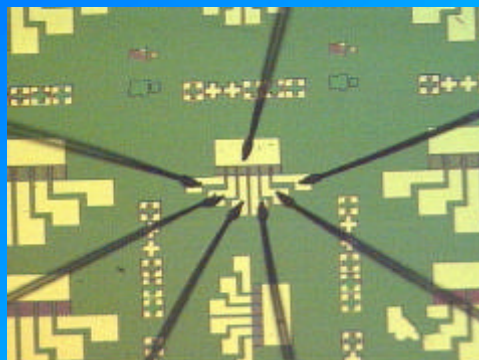
Devices fabricated for tests



MSM GaN device



Schottky GaN device



1x 6 linear micro-array of
MSM photodiodes
fabricated on
AlGaN/Si(111) samples

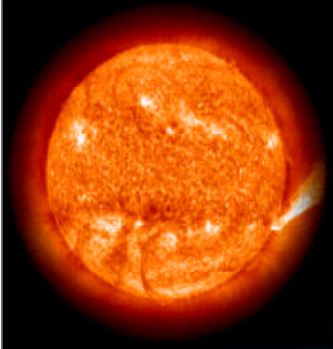
SPIE Annual Meeting, San Diego
3 - 8 August 2003



ISOM-UPM

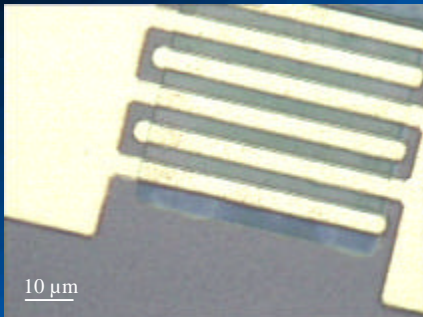


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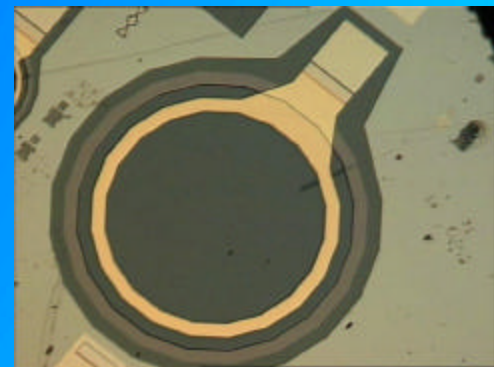
Single-photodetectors

Metal-semiconductor-metal



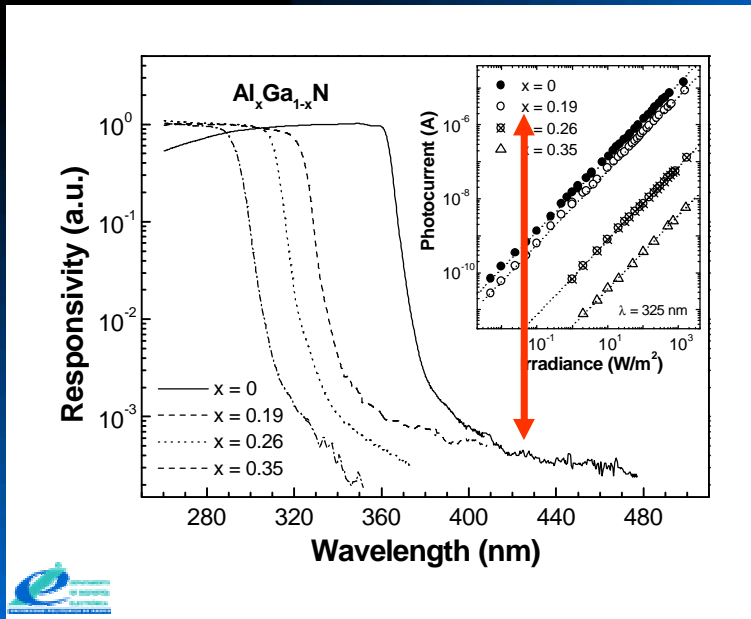
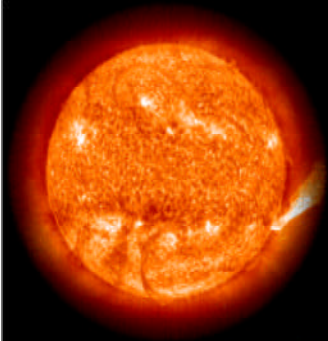
- Active areas: 500 x 500 μm²
250 x 250 μm²
50 x 50 μm²
30 x 30 μm²
- Finger widths (Pt/Ti/Au or Ni/Au)
and spacings: 2,4,7 and 10 μm

Schottky photodiodes



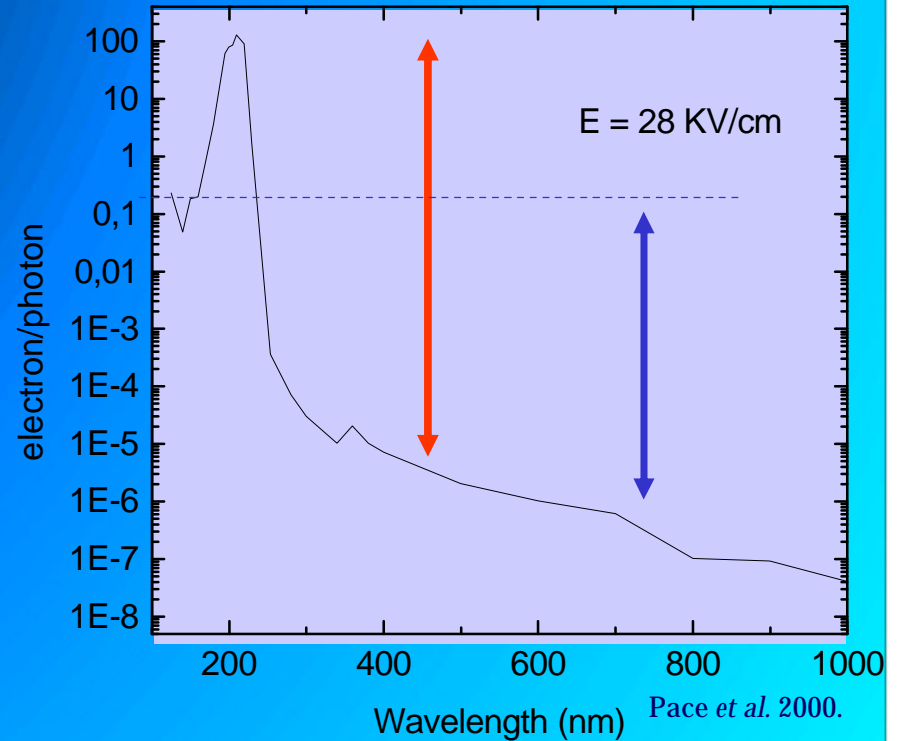
- Extended Ti/Al or Ti/Al/Ti/Au ohmic contact.
- Active areas: 1 mm, 600 μm, 400 μm and 200 μm diameter disks.
- Semitransparent 100 Å-thick Au.
- Ni (300 Å)/ Au (1000 Å) pad.
- Passivation: SiO₂ or SiN.

Solar-blindness of present WBGs detectors



Pau et al. 2003.

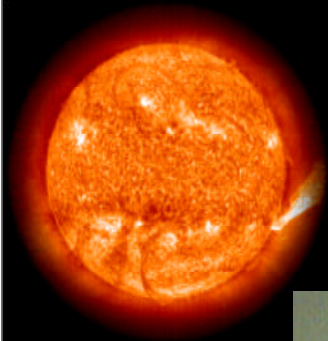
Nitride



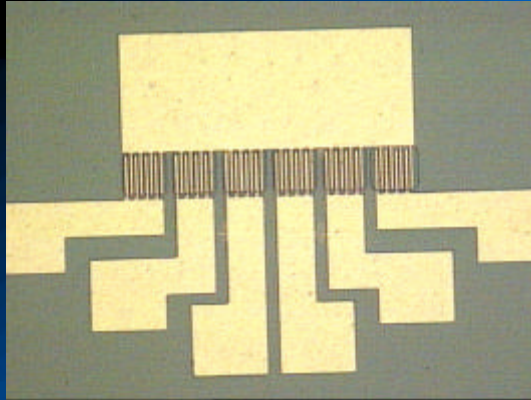
Pace et al. 2000.

Diamond

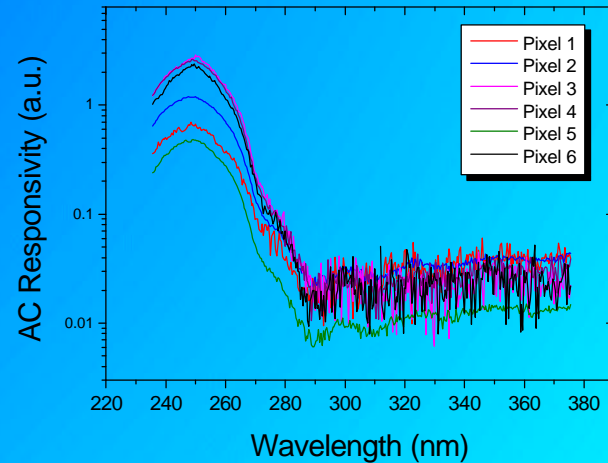
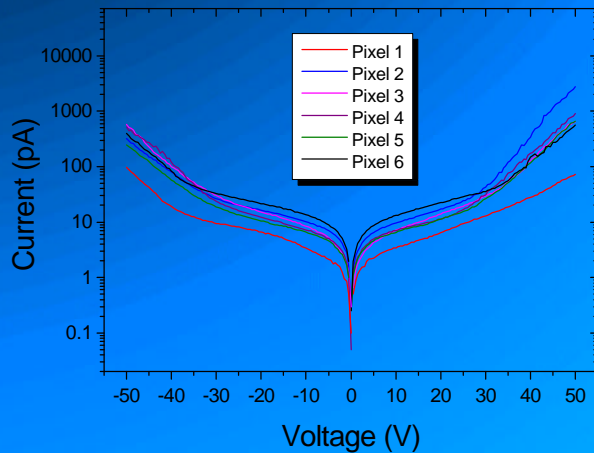




Micro-arrays



- Minimum pixel size: $30 \times 30 \mu\text{m}^2$.
- Finger widths: 2, 4 and 7 μm .
- Homogeneity studies.
- Pixel-to-pixel cross-talk analysis.
- Image persistence effects.

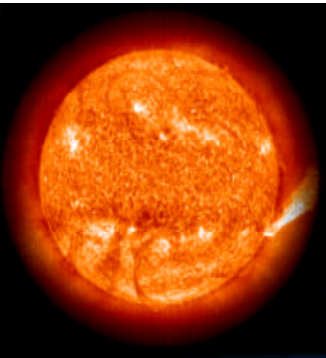


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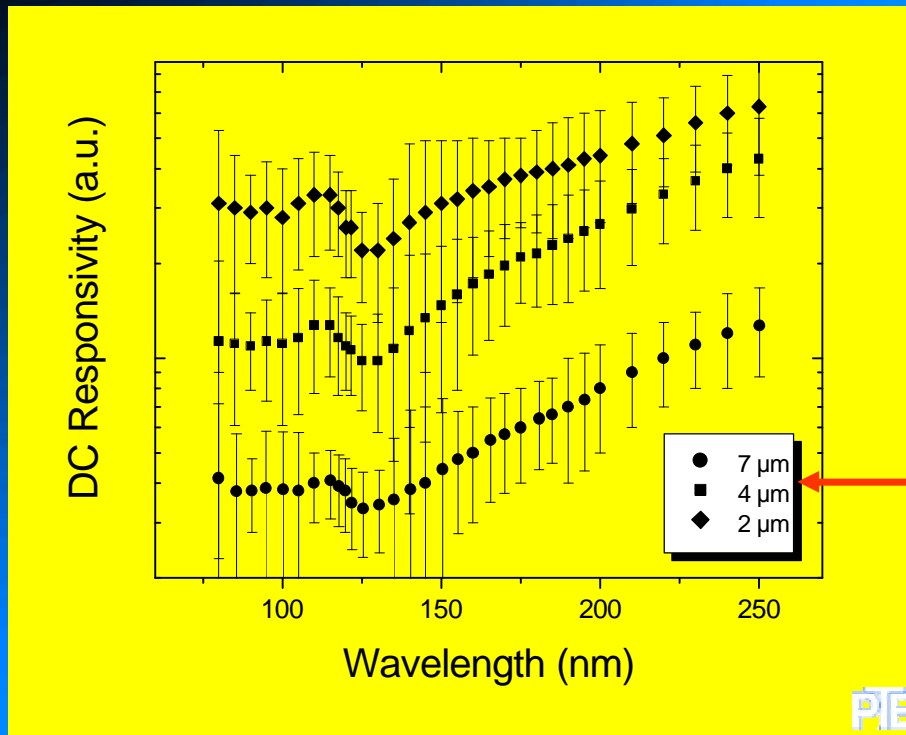
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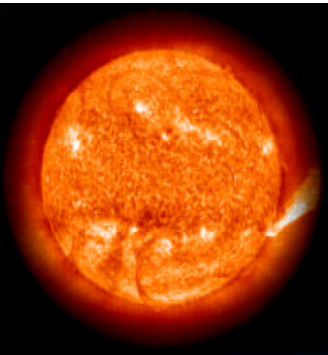
VUV efficiency of MSM GaN devices

Comparison of device structures



Finger width





EUV efficiency of GaN Schottky device

- Absolute responsivity measured at the electron storage ring BESSY II
- Compared to a calibrated PtSi reference diode

